



Attorney Docket No. 5347-223

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Jeffry A. Kelber et al.

Serial No.: 10/785,615

Filed: February 24, 2004

For: CONDUCTORS CREATED BY METAL DEPOSITION USING A SELECTIVE
PASSIVATION LAYER AND RELATED METHODS

April 17, 2006

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Examiner: Tuan T Dinh

Group Art No.: 2841

Confirmation No.: 2942

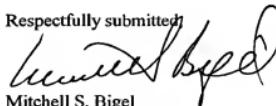
**INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. § 1.97(b)**

Sir:

Attached is a list of documents on Form PTO-1449, together with a copy of any listed foreign patent document and/or non-patent literature. A copy of any listed U.S. patent and/or U.S. patent application publication is not provided herewith in accordance with the amendment by the U.S. Patent and Trademark Office to 37 C.F.R. § 1.98(a)(2)(ii) effective October 21, 2004. It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. § 1.56 and Section 609 of the MPEP.

This Information Disclosure Statement is submitted in accordance with 37 C.F.R. § 1.97(b), within three months of the filing date of the above-referenced application or before the mailing of a first Office Action on the merits, whichever event occurs last. Therefore, no fee is believed due. However, the Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 50-0220.

Respectfully submitted,


Mitchell S. Bigel
Registration No. 29,614

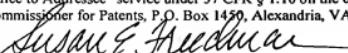
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Susan E. Freedman
Date of Signature: April 17, 2006

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 1 of 2



Complete if Known

Application Number	10/785,615
Filing Date	02/24/2004
First Named Inventor	Jeffry A. Kelber
Group Art Unit	2841
Examiner Name	Tuan T. Dinh
Attorney Docket Number	5347-223

OTHER NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date (page(s), volume-issue numbers), publisher, city and/or country where published	T
	1.	Bertel et al "The Adsorption of Bromine on Pt(111): Observation of an Irreversible Order-Disorder Transition" <i>Surface Science</i> 83:439-452 (1979)	
	2.	Bhaskar et al. "X-ray photoelectron spectroscopy and micro-Raman analysis of conductive RuO ₂ Thin Films" <i>Journal of Applied Physics</i> , 89(5):2987-2992 November '08, 2000	
	3.	Böttcher et al. "Formation of subsurface oxygen at Ru(0001)" <i>The Journal of Chemical Physics</i> 110(6):3186-3195 (1999)	
	4.	Chan et al. "High-Pressure Oxidation of Ruthenium as Probed by Surface-Enhanced Raman and X-Ray Photoelectron Spectroscopies" <i>Journal of Catalysis</i> 172:336-345 (1997)	
	5.	Chyan et al. "Electrodeposition of Copper Thin Film on Ruthenium A Potential Diffusion Barrier for Cu Interconnects" <i>Journal of the Electrochemical Society</i> 150(5):C347-C350 (2003)	
	6.	Cumpson et al. "Elastic Scattering Corrections in AES and XPS. II. Estimating Attenuation Lengths and Conditions Required for their Valid Use in Overlayer/Substrate Experiments" <i>Surface and Interface Analysis</i> 25:430-446 (1997)	
	7.	DiCenzo et al. "XPS Studies of Adatom-Adatom Interactions: I/Ag(111) and I/Cu(111)" <i>Surface Science</i> 121:411-420 (1982)	
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	10.	Grant et al. "A Study of Ru(0001) and Rh(111) Surfaces Using Leed and Auger Electron Spectroscopy" <i>Surface Science</i> 21:76-85 (1970)	
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	13.	Kibler et al. "Initial stages of Pd deposition on Au(hkl) Part I: Pd on Au(111)" <i>Surface Science</i> 443:19-30 (1999)	
	14.	Kim et al. "Chemical state of ruthenium submonolayers on a Pt(111) electrode" <i>Surface Science</i> 474:L203-L212 (2001)	
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	18.	Lin et al. "Combined Ultrahigh Vacuum/Electrochemistry Study of the Adsorption of Lead on Clean and Sulfur-Modified Nickel Surfaces in Aqueous Environments" <i>Langmuir</i> 14:3673-3681 (1998)	
	19.	Liu et al. "The Effects of an Iodine Surface Layer on Ru Reactivity in Air and during Cu Electrodeposition" <i>J. Electrochem. Soc.</i> 152(2):G115-G121 (2005)	
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	26.	Oskam et al. "Electrochemical Deposition of Copper on n-Si/TiN" <i>Journal of the Electrochemical Society</i> 146(4):1436-1441 (1999)	
	27.	Quayum et al. "Mechanism for nucleation and growth of electrochemical palladium deposition on an Au(111) electrode" <i>Journal of Electroanalytical Chemistry</i> 520:126-132 (2002)	
	28.	Reuter et al. "Atomistic description of oxide formation on metal surfaces: the example of ruthenium" <i>Chemical Physics Letters</i> 352:311-317 (2002)	

Examiner Signature

/Tuan Dinh/

Date Considered

01/04/2009

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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INFORMATION DISCLOSURE
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Sheet 2 of 2

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	29.	Seshadri et al. "Sulfur Catalyzed Electrochemical Oxidation of Copper: A Combined Ultrahigh Vacuum Electrochemistry Study" <i>Journal of the Electrochemical Society</i> 146(5):1762-1765 (1999)	
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